

Memory Product Specification

DDR3-1066 SO-DIMM

Description

The Module is DDR3-1066 CL7 Small Outline Memory module. The Module density from 1GB to 2GB, it consists DDR3-1066MHz Synchronous DRAMs in FBGA packages, Memory Module intended for mounting into 204-pin edge connector sockets. The electrical and mechanical specifications are as follows

Features

- JEDEC Standard
- DDR3 Speed Grade : 1066Mbps
- SO-DIMM : 204-pin
- Memory Organization : x8 FBGA DRAM chip
- DDR3 DRAM interface : SSTL_15
- CAS latency : 7-7-7
- Bandwidth : 8.5GB/s
- VDD voltage : 1.5+/-0.075V
- VDDQ voltage : 1.5+/-0.075V
- Serial presence detect with EEPROM.
- PCB height : **1.181 inch**
- RoHS Compliant
- Application : NoteBook